SOT1444-11

WLCSP49, wafer level chip-scale package; 49 bumps; 3.3 mm x 3.3 mm x 0.525 mm body (Backside coating included)

4 February 2019 **Package information**

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP49
Package type industry code	WLCSP49
Package style descriptive code	WLCSP (wafer level chip-size package)
Mounting method type	S (surface mount)
Issue date	22-08-2018
Manufacturer package code	98ASA01205D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	3.3	-	mm
package width	-	3.3	-	mm
package height	-	0.525	-	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	49	-	

2 Package outline

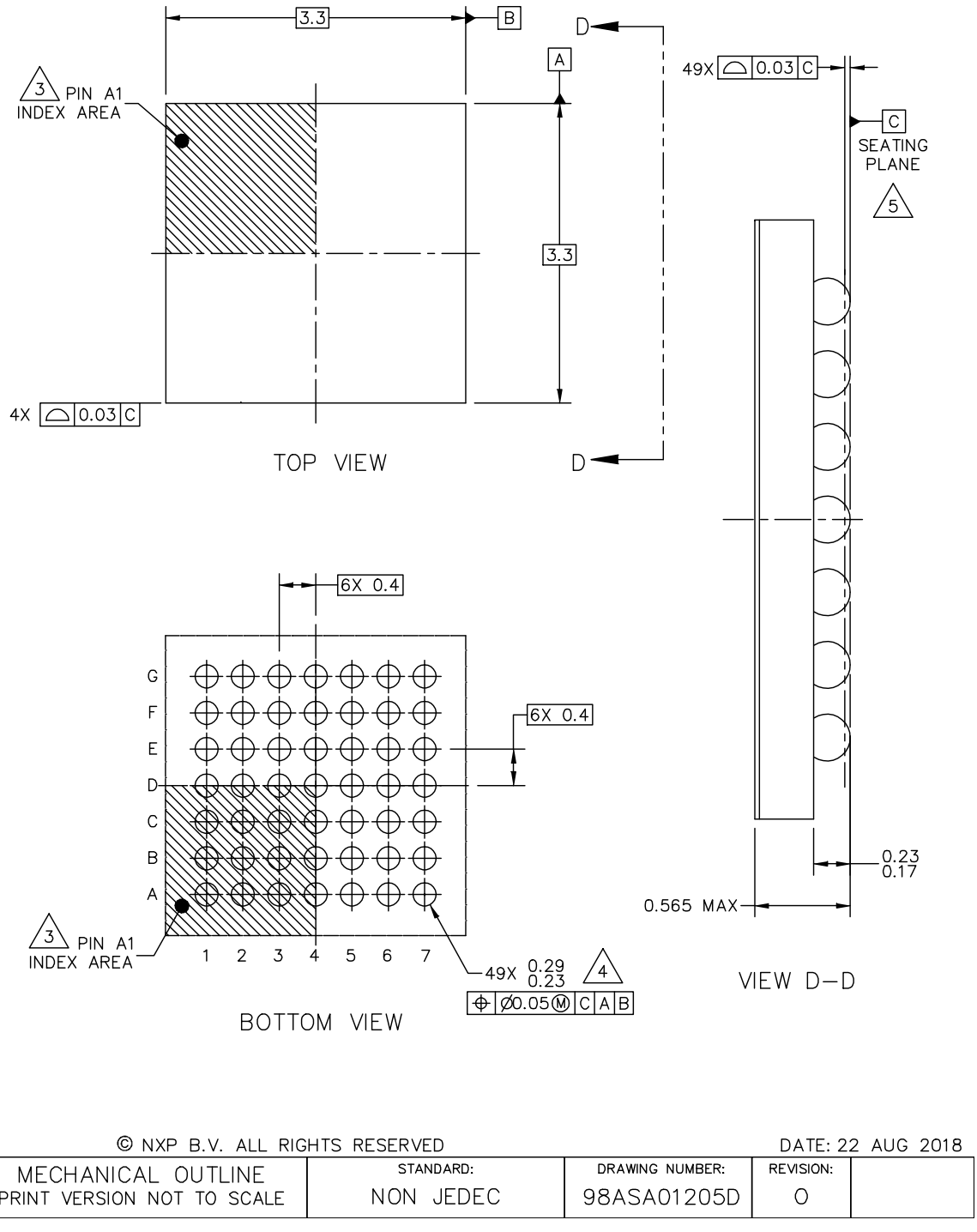
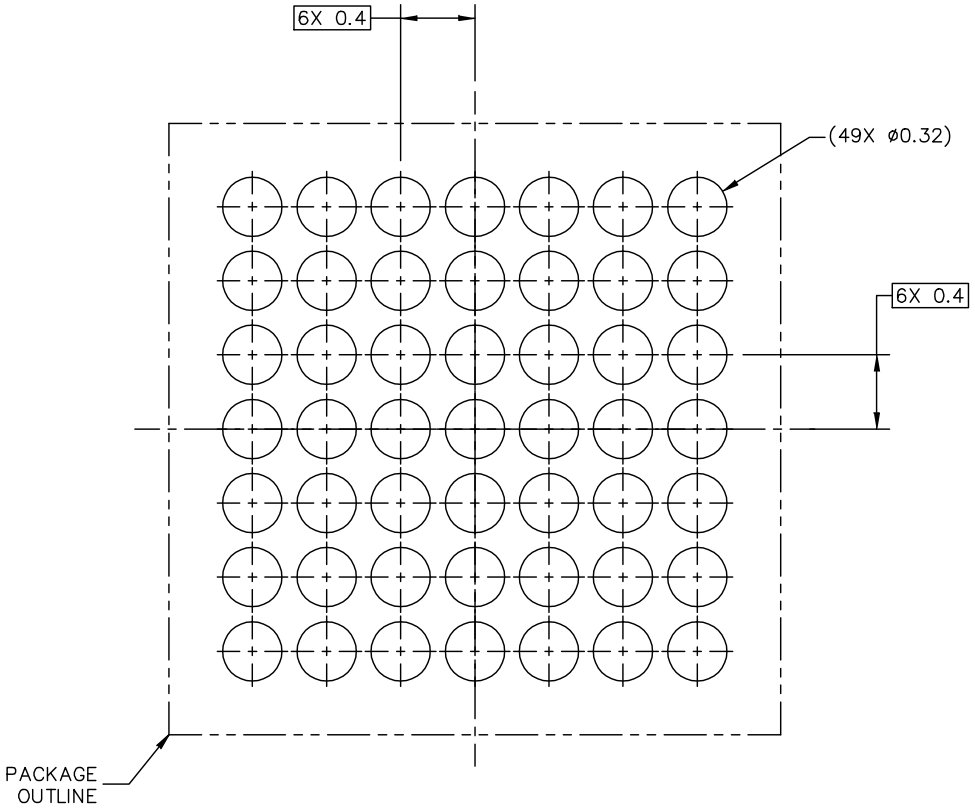


Figure 1. Package outline WLCSP49 (SOT1444-11)

3 Soldering



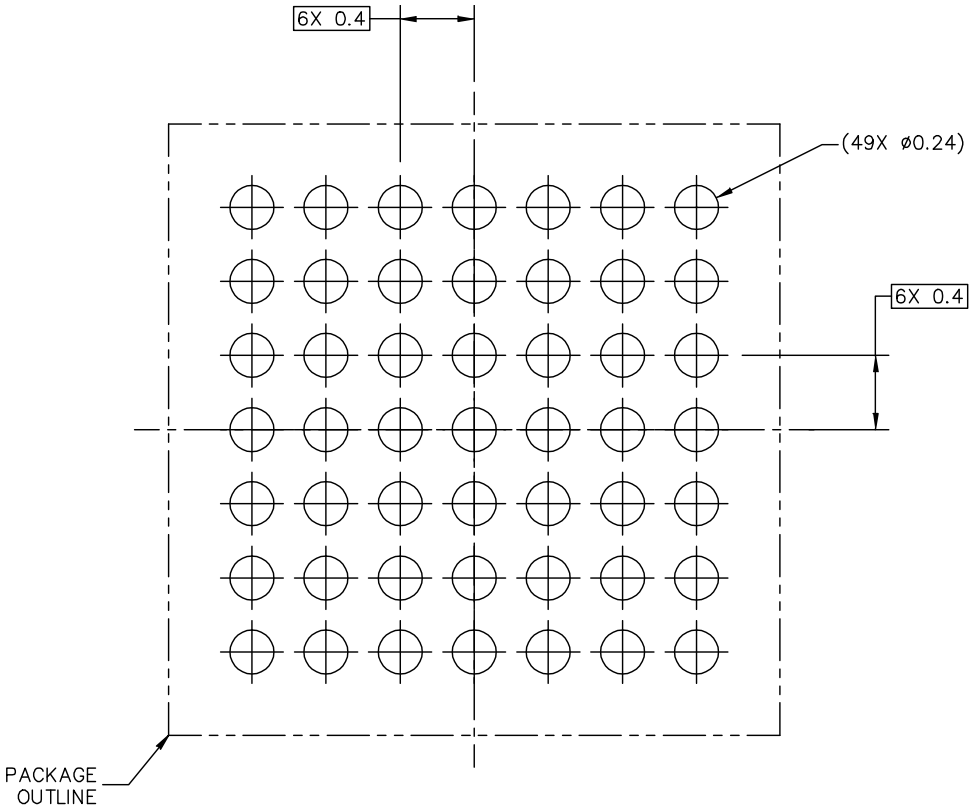
PCB DESIGN GUIDELINES – SOLDER MASK OPENING PATTERN

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

DATE: 22 AUG 2018

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01205D	REVISION: O	

Figure 2. Reflow soldering footprint part1 for WLCSP49 (SOT1444-11)



PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

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DATE: 22 AUG 2018

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01205D	REVISION: O	

Figure 3. Reflow soldering footprint part2 for WLCSP49 (SOT1444-11)

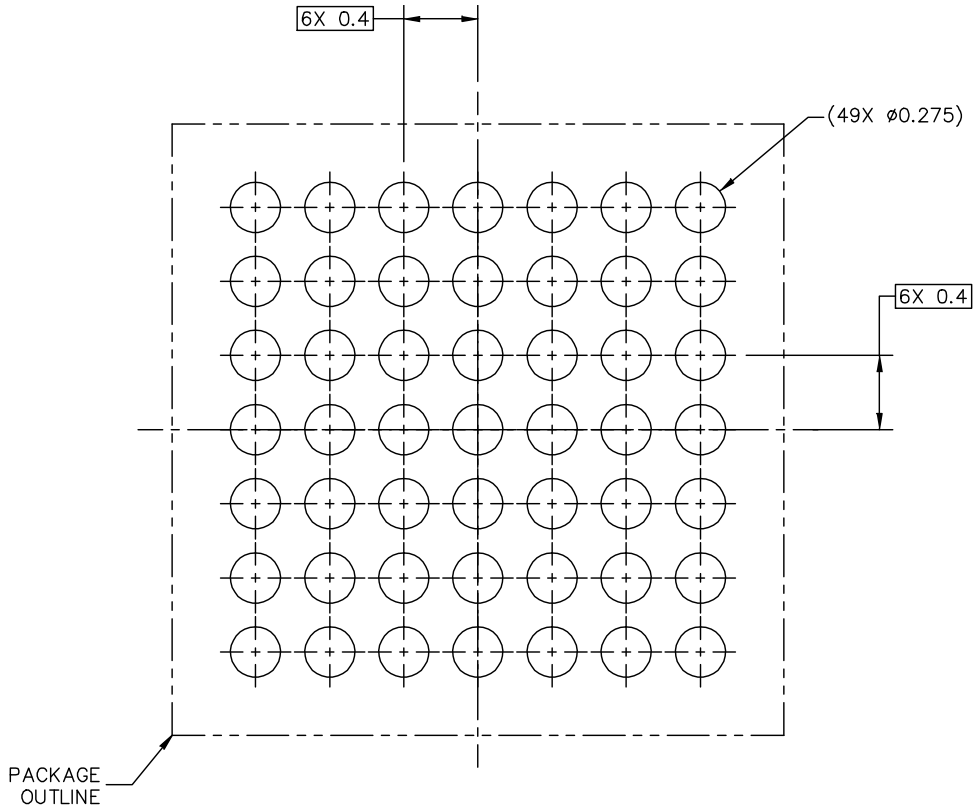

Figure 4. Reflow soldering footprint part3 for WLCSP49 (SOT1444-11)

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.
3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. THIS PACKAGE HAS A BACK SIDE COATING THICKNESS OF 0.025.

DATE: 22 AUG 2018

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01205D	REVISION: O	

Figure 5. Package outline note WLCSP49 (SOT1444-11)

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Contents

For more information, please visit: http://www.nxp.com
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